N-Channel Enhancement Mode MOSFET

Description

The NVMFS5H663NLWFT1G uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 60V I_{D} = 80 A$

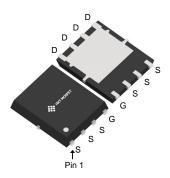
 $R_{DS(ON)} < 7m\Omega$ @ V_{GS} =10V

Application

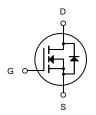
Battery protection

Load switch

Uninterruptible power supply



DFN5X6-8L (TDSON-8)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
NVMFS5H663NLWFT1G	DFN5X6-8L(TDSON-8)	HXY MOSFET	5000

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units		
V _D s	Drain-Source Voltage	Drain-Source Voltage 60			
Vgs	Gate-Source Voltage	±20	V		
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	80	А		
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	52	А		
Ірм	Pulsed Drain Current ²	320	А		
EAS	Single Pulse Avalanche Energy³	169	mJ		
P _D @T _C =25°C	Total Power Dissipation ⁴	108	W		
Тѕтс	Storage Temperature Range	-55 to 150	°C		
TJ	Operating Junction Temperature Range	-55 to 150	°C		
Reuc	Thermal Resistance Junction-Case ¹	1.4	°C/W		

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Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristics	,				1
V _{(BR)D} s	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μΑ
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Charac	cteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	3	4	V
R _{DS(on)}	Static Drain-Source on-Resistance	V _{GS} =10V, I _D = 30A	- 5.3		7	mΩ
Dynamic (Characteristics					1
C _{iss}	Input Capacitance	V _{DS} =30V,	-	4136	-	pF
Coss	Output Capacitance	V _{GS} =0V,	-	286	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	257	-	pF
Qg	Total Gate Charge	\/ -20\/	-	90	-	nC
Q _{gs}	Gate-Source Charge	V _{DS} =30V,	-	9	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	I _D =30A, V _{GS} =10V	-	18	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	9	-	ns
t _r	Turn-on Rise Time	V _{DS} =30V, I _D =30A,	-	7	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =1.8Ω, V _{GS} =10V	-	40	-	ns
t _f	Turn-off Fall Time		1	15	1	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	А
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		_	-	320	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0VI _S =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge	y I _F =30A, dI/dt=100A/μs		46	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} EAS condition : T_J =25°C, V_{DD} =30V, V_G =10V, L=0.5mH, Rg=25 Ω , I_{AS} =26A

^{3.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

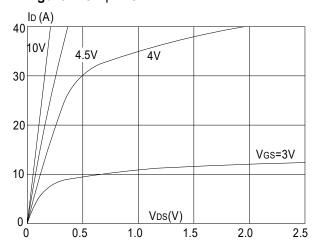


Figure 3:On-resistance vs. Drain Current

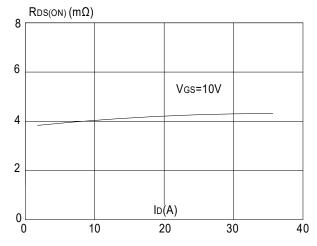


Figure 5: Gate Charge Characteristics

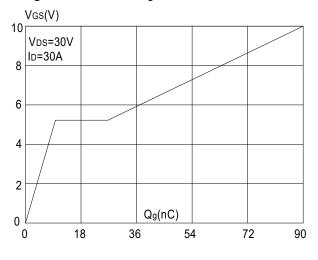


Figure 2: Typical Transfer Characteristics

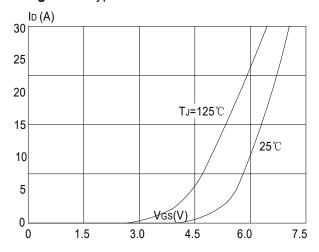


Figure 4: Body Diode Characteristics

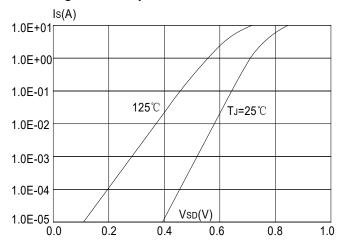
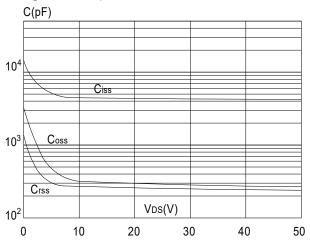


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

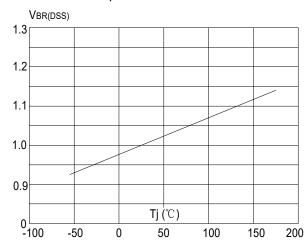


Figure 8: Normalized on Resistance vs. Junction Temperature

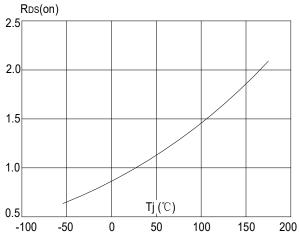


Figure 9: Maximum Safe Operating Area

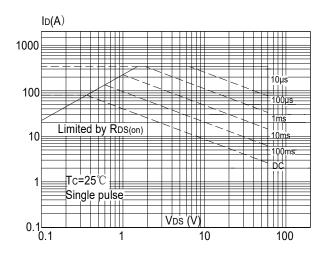


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

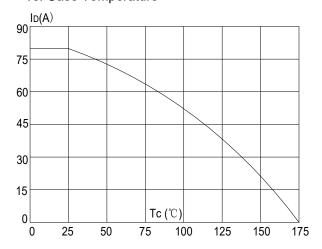
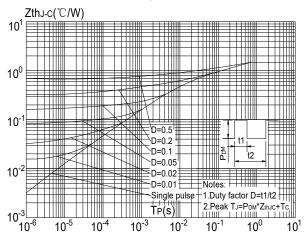
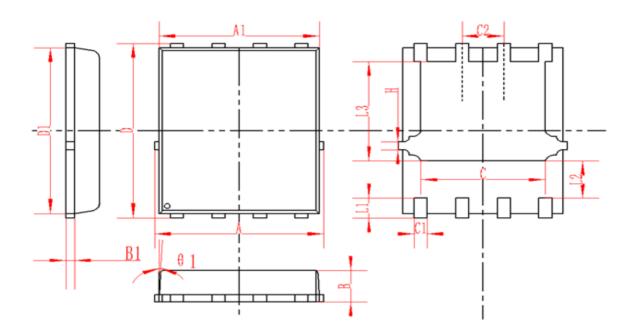


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



DFN5X6-8L(TDSON-8) Package Information



SYMBOL		MM		INCH			
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX	
А	4.95	5	5.05	0.195	0.197	0.199	
A1	4.82	4.9	4.98	0.190	0.193	0.196	
D	5.98	6	6.02	0.235	0.236	0.237	
D1	5.67	5.75	5.83	0.223	0.226	0.230	
В	0.9	0.95	1	0.035	0.037	0.039	
B1	0.254REF		0.010REF				
С	3.95	4	4.05	0.156	0.157	0.159	
C1	0.35	0.4	0.45	0.014	0.016	0.018	
C2		1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°	
L1	0.63	0.64	0.65	0.025	0.025	0.026	
L2	1.2	1.3	1.4	0.047	0.051	0.055	
L3	3.415	3.42	3.425	0.134	0.135	0.135	
Н	0.24	0.25	0.26	0.009	0.010	0.010	

NVMFS5H663NLWFT1G

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